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Intel - 5SGXEB5R2F43I3LN Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	41984000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-FCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeb5r2f43i3In

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I 3YY	14
3		Yes	Yes	Yes		Yes	Yes (4)	Yes
GX channel—8.5 Gbps		165	165	165		163	163 17	165

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices. **Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering** ⁽¹⁾, ⁽²⁾

Transaction Oracle Oracle		Core Speed Grade						
Transceiver Speed Grade	C1	C2	12	13				
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_				
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes				

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3.	Absolute	Maximum	Ratings	for Stratix \	/ Devices	(Part 1 of 2)
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Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	CV CS CT	0.87	0.90	0.93	v
(2)	Receiver analog power supply (right side)	GX, GS, GT	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL} T	Transmitter analog newer supply (left side)	GX, GS, GT	0.87	0.90	0.93	- V
	Transmitter analog power supply (left side)	un, uo, ui	0.97	1.0	1.03	
			1.03	1.05 1.07	1.07	
			0.82	0.85	0.88	
V _{CCT_GXBR}	Transmitter analog nower supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Table 7.	Recommended Transceiver Power Supply Operating Conditions for Stratix V GX,	GS, and GT Devices
(Part 2	of 2)	

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- ***** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Symbol/	Conditions	Transceiver Speed Grade 1		Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1	_	2	_	—	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2	_	4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	—	dB
Transmitter											
Supported I/O Standards	_		1.4-V and 1.5-V PCML								
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600		12500	600		8500/ 10312.5 (24)	Mbps
	85-Ω setting		85 ± 20%	_	_	85 ± 20%		_	85 ± 20%	_	Ω
Differential on-	100-Ω setting	_	100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%			120 ± 20%		_	120 ± 20%		Ω
	150-Ω setting		150 ± 20%		_	150 ± 20%			150 ± 20%		Ω
V _{OCM} (AC coupled)	0.65-V setting		650		_	650		_	650	_	mV
V _{OCM} (DC coupled)	_		650		_	650		_	650	_	mV
Rise time (7)	20% to 80%	30		160	30		160	30		160	ps
Fall time ⁽⁷⁾	80% to 20%	30		160	30		160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps			15			15			15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode			120			120			120	ps

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 5 of 7)

Symbol/ Description Conditions		Transceiver Speed Grade 1		Transceiver Speed Grade 2		Transceiver Speed Grade 3			Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_			10		—	10	—		10	μs

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 7 of 7)

Notes to Table 23:

(2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.

(3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.

- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll_powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{pll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{BEF} is 2000 $\Omega \pm 1\%$.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

⁽¹⁾ Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.

Table 27 shows the V_{OD} settings for the GX channel.

Symbol	V _{op} Setting	V _{op} Value (mV)	V _{op} Setting	V _{op} Value (mV)
	0 (1)	0	32	640
	1 ⁽¹⁾	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 (1)	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
V _{op} differential peak to peak	15	300	47	940
typical ⁽³⁾	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Table 27. Typical V_{0D} Setting for GX Channel, TX Termination = 100 $\Omega^{\left(2\right)}$

Note to Table 27:

(1) If TX termination resistance = 100Ω , this VOD setting is illegal.

(2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.

(3) Refer to Figure 2.

Symbol/	Conditions	Transceiver Speed Grade 2				Transceive peed Grade		Unit		
Description		Min	Тур	Max	Min	Тур	Max			
Reference Clock										
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LV and HCSL								
	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	6		
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz		
Input Reference Clock Frequency (ATX PLL) ⁽⁶⁾	_	100	-	710	100	_	710	MHz		
Rise time	20% to 80%		_	400		—	400			
Fall time	80% to 20%			400	—		400	ps		
Duty cycle	—	45		55	45		55	%		
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz		
Spread-spectrum downspread	PCle	_	0 to -0.5		_	0 to -0.5	_	%		
On-chip termination resistors ⁽¹⁹⁾	_	_	100	_	_	100	_	Ω		
Absolute V _{MAX} ⁽³⁾	Dedicated reference clock pin		_	1.6	_	_	1.6	V		
	RX reference clock pin	_	_	1.2	_	_	1.2			
Absolute V _{MIN}	—	-0.4	—	—	-0.4	—	—	V		
Peak-to-peak differential input voltage	_	200		1600	200	_	1600	mV		
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000 (2)		1050/1000 (2)	mV		
	RX reference clock pin	1	.0/0.9/0.85 (22)	1	.0/0.9/0.85 (22)	V		
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV		

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) ⁽¹⁾

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
	85- Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels ⁽¹⁹⁾	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth		700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μs
t _{LTD} ⁽¹⁰⁾		4			4			μs
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	_	μs
t _{LTR_LTD_manual} ⁽¹²⁾	_	15			15	—		μs
Run Length	GT channels	_	_	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1							
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)⁽¹⁾

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{finpfd}	Fractional Input clock frequency to the PFD	50	—	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO}	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 ⁽²⁾	MHz
f _{оит}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{out_ext}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	—	10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t _{olock}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift			±50	ps
t _{areset}	Minimum pulse width on the areset signal	10	_		ns

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter		Тур	Max	Unit
f _{RES}	Resolution of VCO frequency ($f_{INPFD} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.05-0.95 must be \geq 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.20-0.80 must be \geq 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

			I	Peforman	ce			
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ising one	DSP				4
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two l	DSPs	1		•	1
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 33:

(1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50**% output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

(2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

(3) The F_{MAX} specification is only achievable with Fitter options, MLAB Implementation In 16-Bit Deep Mode enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	—	200	μA
V _{bias,} voltage across diode	0.3	—	0.9	V
Series resistance		—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	

i ani o o o i i i i gii	-Speed I/U Specifica		C1				2, I2L		-	., I3YY		C4 L	A	
Symbol	Conditions				-	-	-		-	-		C4,I4 Min Tyn May	Unit	
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{duty}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t _{rise} & t _{fall}	Emulated Differential I/O Standards with three external output resistor networks			250			250			250			300	ps
	True Differential I/O Standards	_	_	150	_	_	150	_	_	150	_	_	150	ps
TCCS	Emulated Differential I/O Standards	_		300	_	_	300	_	_	300	_	_	300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150		1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150		1600	150		1600	150		1600	150		1250	Mbps
- f _{HSDRDPA} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

rx_reset	i		
rx_dpa_locked			

Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only (1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁴⁾	Maximum
SPI-4	0000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
Wiscenardous	01010101	8	32	640 data transitions

Notes to Table 37:

(1) The DPA lock time is for one channel.

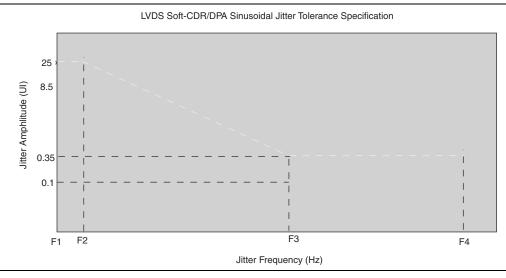
(2) One data transition is defined as a 0-to-1 or 1-to-0 transition.

(3) The DPA lock time stated in this table applies to both commercial and industrial grade.

(4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps.



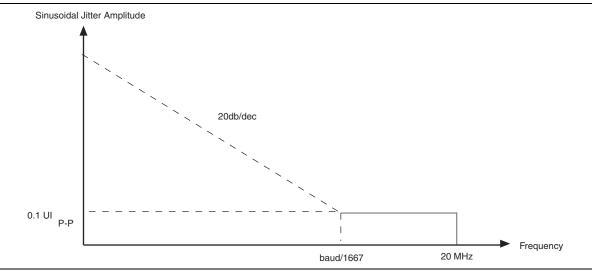


Jitter Fre	Sinusoidal Jitter (UI)			
F1	10,000	25.000		
F2	17,565	25.000		
F3	1,493,000	0.350		
F4	F4 50,000,000			

Table 38.	LVDS Soft-CDR/D	PA Sinusoidal	Jitter Mask Valu	es for a Data Ra	te > 1.25 Gbps
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Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.





DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

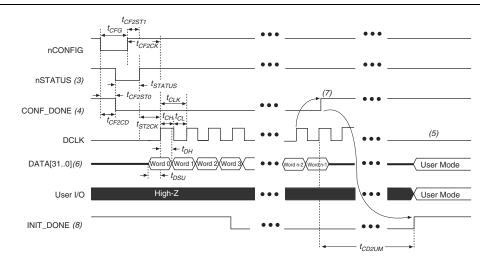
Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices ^{(1), (2)} (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.





Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nstatus low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT DONE goes low.

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{cd2cu} + (8576 × clkusr period)	_	—

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

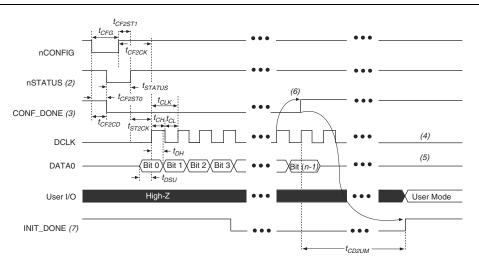
(2) t_{CF2CD}, t_{CF2ST0}, t_{CF2ST0}, t_{CF6}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds <code>nSTATUS</code> low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} ⁽¹⁾	250	—	ns
t _{RU_nRSTIMER} ⁽²⁾	250	—	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

 You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Deremeter	Available	Min		Model				Slow N	lodel			
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Table 60.	Glossary	(Part 3 of 4)
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Letter	Subject	Definitions					
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown: Bit Time 0.5 x TCCS RSKM Sampling Window RSKM 0.5 x TCCS RSKM					
S	Single-ended voltage referenced I/O standard	The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: <i>Single-Ended Voltage Referenced I/O Standard</i> 					
	t _C	High-speed receiver and transmitter input and output clock period.					
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).					
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.					
т	t _{DUTY}	Timing Unit Interval (TUI) The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_c/w)$					
	t _{FALL}	Signal high-to-low transition time (80-20%)					
	t _{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.					
	t _{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.					
	t _{outpj_dc}	Period jitter on the dedicated clock output driven by a PLL.					
	t _{RISE}	Signal low-to-high transition time (20-80%)					
U	_	_					

Table 61. Document Revision History (Part 3 of 3)

Date	Version	Changes
		■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60
May 2013	2.7	■ Added Table 24, Table 48
		 Updated Figure 9, Figure 10, Figure 11, Figure 12
February 2013	2.6	 Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46
		 Updated "Maximum Allowed Overshoot and Undershoot Voltage"
		 Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35
		Added Table 33
		 Added "Fast Passive Parallel Configuration Timing"
December 0010	0.5	 Added "Active Serial Configuration Timing"
December 2012	2.5	 Added "Passive Serial Configuration Timing"
		 Added "Remote System Upgrades"
		 Added "User Watchdog Internal Circuitry Timing Specification"
		 Added "Initialization"
		 Added "Raw Binary File Size"
June 2012		 Added Figure 1, Figure 2, and Figure 3.
	2.4	 Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.
		 Various edits throughout to fix bugs.
		 Changed title of document to Stratix V Device Datasheet.
		 Removed document from the Stratix V handbook and made it a separate document.
February 2012	2.3	■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.
December 2011	ber 2011 2.2	■ Added Table 2–31.
	2.2	■ Updated Table 2–28 and Table 2–34.
Neurometren 0011	0.1	 Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.
November 2011	2.1	■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.
		 Various edits throughout to fix SPRs.
		 Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.
May 2011	2.0	 Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications" title.
		 Chapter moved to Volume 1.
		 Minor text edits.
		■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.
December 2010	1.1	 Converted chapter to the new template.
		 Minor text edits.
July 2010	1.0	Initial release.